High Voltage LED Series Chip on Board

LCo19D-Gen.1



High efficacy COB LED package well-suited for use in spotlight applications









Features & Benefits

- Chip on Board (COB) solution makes it easy to design in
- · Simple assembly reduces manufacturing cost
- · Low thermal resistance
- InGaN/GaN MQW LED with long time reliability

Applications

- Spotlight / Downlight
- LED Retrofit Bulbs
- Outdoor Illumination



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1. Characteristics

a) Absolute Maximum Rating

ltem	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	Ta	-40 ~ +105	°C	-
Storage Temperature	T_{stg}	-40 ~ +120	°C	-
LED Junction Temperature	TJ	140	°C	-
Case Temperature	Tc	105	°C	
Forward Current	l _F	1380	mA	-
Power Dissipation	P _D	51.8	W	-
ESD (HBM)	-	±2	kV	-
ESD (MM)	-	±0.5	kV	-

b) Electro-optical Characteristics ($I_F = 540 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C}$)

ltem	Unit	Rank	Min.	Тур.	Max.
Forward Voltage (V _F)	V	YZ	31.8	34.6	37.5
Color Pandering Index (P.)		5	80	-	-
Color Rendering Index (R _a)	-	7	90		
Thermal Resistance (junction to chip point)	°C/W		-	1.0	-
Beam Angle	0		-	115	-
Nominal Power	W			20.3	

Notes:

- 1) The COB is tested in pulsed condition at rated test current (10 ms pulse width) and rated temperature ($T_J = T_C = T_a = 85$ °C)
- 2) Samsung maintains measurement tolerance of: forward voltage = ± 5 %, CRI = ± 1
- 3) Refer to the derating curve, '3. Typical Characteristics Graph' designed within the range.

c) Luminous Flux Characteristics (I_F = 540 mA)

CRI (R _a)	Nominal	Flux		Flux @ T _J = 85 °C (lm)
Min.	CCT (K)	Rank	Min.	Тур.	Max.
	2700	J3	2335	2458	-
	2100	D1	2458	2581	-
	2000	J4	2462	2592	-
	3000	D1	2592	2722	-
	3500	J5	2538	2672	-
		D1	2672	2805	-
80	4000	J5	2590	2726	-
ou ou		D1	2726	2863	-
	5000	J6	2618	2756	-
	5000	D1	2756	2894	-
	5700	J6	2618	2756	-
	5700	D1	2756	2894	-
	6500	J5	2590	2726	-
		D1	2726	2863	-

CRI (R _a)	Nominal	Flux	Flux @ T _J = 85 °C (lm)			
Min.	CCT (K)	Rank	Min.	Тур.	Max.	
	2700	Н9	1999	2104	-	
	2700	D1	2104	2210	-	
	2000	J0	2096	2207	-	
	3000	D1	2207	2317	-	
90	3500	J1	2173	2287	-	
90		D1	2287	2402	-	
	4000	J2	2220	2337	-	
	4000	D1	2337	2454	-	
	5000	J2	2222	2339		
		D1	2339	2456		

Notes:

- 1) The COB is tested in pulsed operating condition at rated test current (10 ms pulse width) and rated temperature $(T_J = T_C = 85 \, ^{\circ}C)$.
- 2) Samsung maintains measurement tolerance of: Luminous flux = ± 7 %, CRI = ± 1

2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	Р	н	w	н	Α	н	D	N	F	2	5	Υ	Z	W	3	J	3

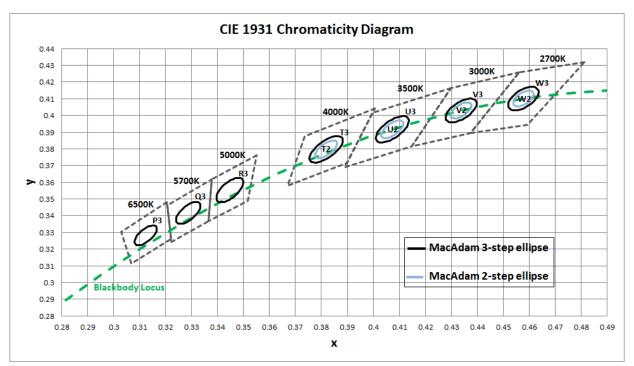
Digit	PKG Information	Code	Specification Specification
1 2 3	Samsung Package High Power	SPH	
4 5	Color	WH	White
6	Product Version	Α	
7 8	Form Factor	HD	СОВ
9	Lens Type	N	No lens
10	Wattage or Model	F	LC019D
11	Internal Code	2	
12	CRI & Sorting Temperature	5	Min. 80 (85°C)
12	Civi & Conting Temperature	7	Min. 90 (85°C)
13 14	Forward Voltage (V)	YZ	31.8~37.5
15	CCT (K)	W V U T R Q	2700K 3000K 3500K 4000K 5000K 5700K 6500K
16	MacAdam Step	3	MacAdam 2-step MacAdam 3-step
17 18	Luminous Flux	H9 J0 J1 J2 J3 J4 J5 J6	Min. 1900 Min. 2000 Min. 2100 Min. 2200 Min. 2300 Min. 2400 Min. 2500 Min. 2600

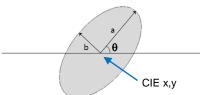
a) Binning Structure (I_F = 540 mA, T_J = 85 °C)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Flux Rank	Flux Range (Φ _ν , lm)
		SPHWHAHDNF25YZW2J3		W2	- J3	2335 ~
	2700	SPHWHAHDNF25YZW3J3	YZ	W3	J3	2335 ~
	2700	SPHWHAHDNF25YZW2D1	YZ	W2	- D1	2458 ~
		SPHWHAHDNF25YZW3D1	••••	W3	DI	2438 ~
		SPHWHAHDNF25YZV24		V2	14	2462 ~
	3000	SPHWHAHDNF25YZV3J4	YZ	V3	J4	2402 ~
	3000	SPHWHAHDNF25YZV2D1	12	V2	D1	2592 ~
		SPHWHAHDNF25YZV3D1		V3	DI	2592 ~
		SPHWHAHDNF25YZU25		U2	- J5	2538 ~
	3500	SPHWHAHDNF25YZU3J5	YZ	U3	2550 ~	
80		SPHWHAHDNF25YZU2D1		U2	·· D1	2672 ~
00		SPHWHAHDNF25YZU3D1		U3		2072 ~
		SPHWHAHDNF25YZT25		T2	J5	2590 ~
	4000	SPHWHAHDNF25YZT3J5	YZ	Т3		2000
	4000	SPHWHAHDNF25YZT2D1		T2	D1	2726 ~
		SPHWHAHDNF25YZT3D1		Т3		2.20
	5000	SPHWHAHDNF25YZR3J6	YZ	R3	J6	2618 ~
		SPHWHAHDNF25YZR3D1			D1	2756 ~
	5700	SPHWHAHDNF25YZQ3J6	YZ	Q3	J6	2618 ~
	3700	SPHWHAHDNF25YZQ3D1	1 4		D1	2756 ~
	6500	SPHWHAHDNF25YZP3J5	V7 D2	J5	2590 ~	
	0300	SPHWHAHDNF25YZP3D1	12	YZ P3 D1		2726 ~

CRI (R _a) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Flux Rank	Flux Range (Φ _v , lm)
		SPHWHAHDNF27YZW2H9		W2	40	1999 ~
	2700	SPHWHAHDNF27YZW3H9 W2	1999 ~			
	2700	SPHWHAHDNF27YZW2D1	YZ	W2	D1	2104 ~
		SPHWHAHDNF27YZW3D1		W2	DI	2104 ~
		SPHWHAHDNF27YZV2J0		V2	J0	2096 ~
	3000	SPHWHAHDNF27YZV3J0	····· YZ	V3	JU	2090 ~
	3000	SPHWHAHDNF27YZV2D1		V2	D1	2207 ~
		SPHWHAHDNF27YZV3D1		V3	D1	2201 ~
90		SPHWHAHDNF27YZU2J1		U2	··· J1	2173 ~
90	3500	SPHWHAHDNF27YZU3J1	YZ	U3	31	2173~
	3300	SPHWHAHDNF27YZU2D1		U2	D1	2287 ~
		SPHWHAHDNF27YZU3D1		U3	D1	2201 ~
		SPHWHAHDNF27YZT2J2		T2	J2	2220 ~
	`4000	SPHWHAHDNF27YZT3J2	YZ	Т3	32	2220 ~
	4000	SPHWHAHDNF27YZT2D1		T2	D1	2337 ~
		SPHWHAHDNF27YZT3D1		Т3	DI	2001 ~
	5000	SPHWHAHDNG27YZR3J8	YZ	R3	J8	2222 ~
	5000	SPHWHAHDNG27YZR3D1	1 4	R3	D1	2339 ~

b) Chromaticity Region & Coordinates ($I_F = 540 \text{ mA}, T_J = 85 \, ^{\circ}\text{C}$)





	MacAdam Ellipse (W2, W3)										
Step	CIE x	CIE y									
2-step	0.4578	0.4101	53.70	0.0054	0.0028						
3-step	0.4578	0.4101	53.70	0.0081	0.0042						

MacAdam Ellipse (V2, V3)										
Step	CIE x	CIE y								
2-step	0.4338	0.403	53.22	0.0056	0.0027					
3-step	0.4338	0.4030	53.22	0.0083	0.0041					

MacAdam Ellipse (U2, U3)										
Step	CIE x	CIE y								
2-step	0.4073	0.3917	54.00	0.0062	0.0028					
3-step	0.4073	0.3917	54.00	0.0093	0.0041					

MacAdam Ellipse (T2, T3)						
Step	CIE x	CIE y				
2-step	0.3818	0.3797	53.72	0.0063	0.0027	
3-step	0.3818	0.3797	53.72	0.0094	0.0040	

MacAdam Ellipse (R3)						
Step	CIE x	CIE y				
3-step	0.3447	0.3553	59.62	0.0082	0.0035	

MacAdam Ellipse (Q3)							
Step CIE x CIE y θ a b							
3-step	0.3287	0.3417	59.0950	0.0075	0.0032		

MacAdam Ellipse (P3)							
Step CIE x CIE y θ a b							
3-step 0.3123 0.3282 58.5700 0.0067 0.0029							

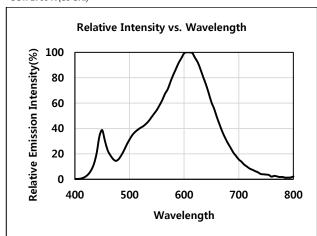
Note:

Samsung maintains measurement tolerance of: Cx, $Cy = \pm 0.005$

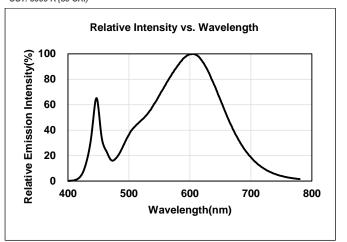
3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_F = 540 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C}$)

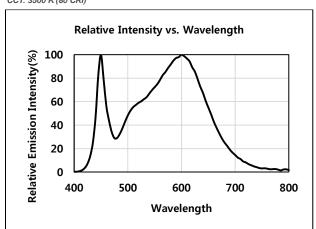
CCT: 2700 K (80 CRI)



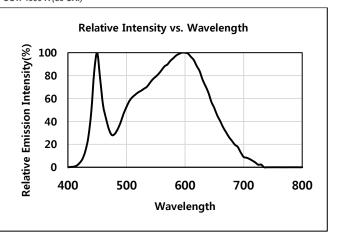
CCT: 3000 K (80 CRI)



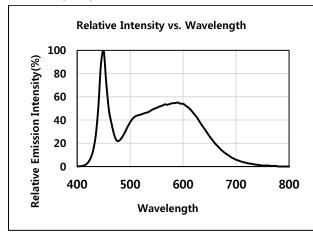
CCT: 3500 K (80 CRI)



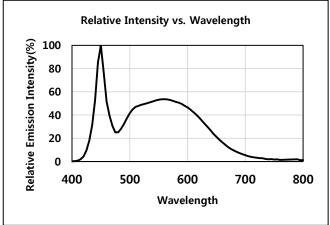
CCT: 4000 K (80 CRI)



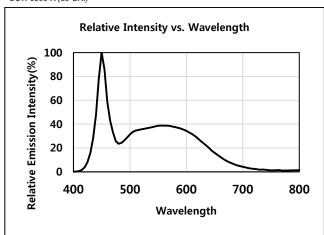
CCT: 5000 K (80 CRI)



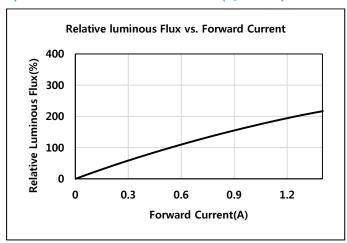
CCT: 5700 K (80 CRI)

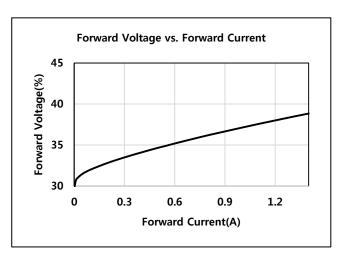


CCT: 6500 K (80 CRI)

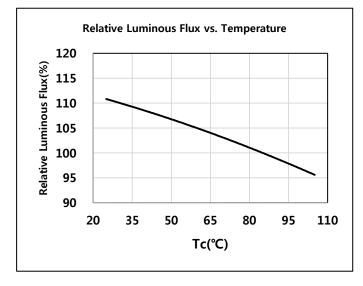


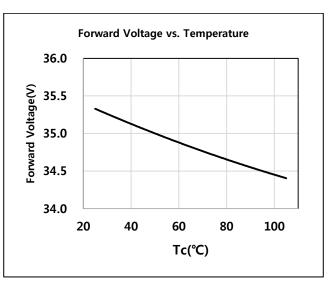
b) Forward Current Characteristics (T_J = 85 °C)



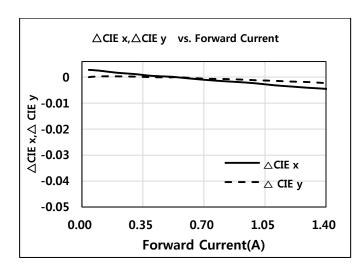


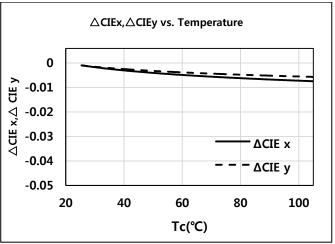
C) Temperature Characteristics (I_F = 540mA)



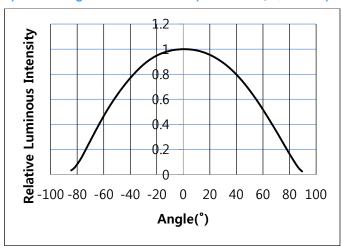


d) Color Shift Characteristics $(T_J = 85 \, {}^{\circ}\text{C}, I_F = 540 \, \text{mA}, CR180+)$

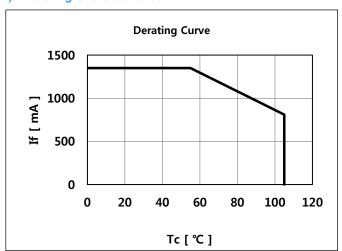




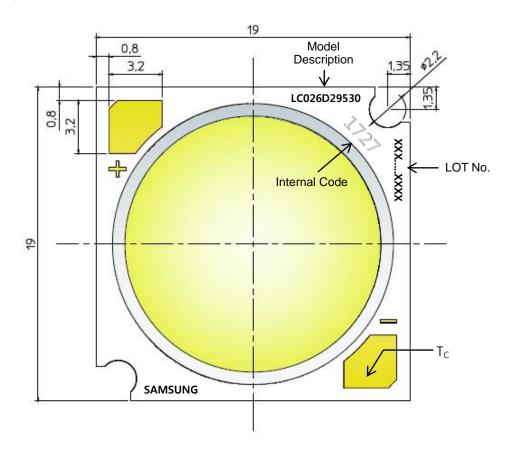
e) Beam Angle Characteristics ($I_F = 540 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C}$)

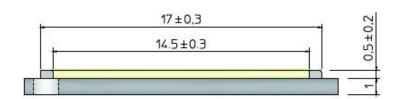


f) Derating Characteristics



4. Outline Drawing & Dimension





Unit: mm
 Tolerance: ± 0.3 mm

ltem	Dimension	Tolerance	Unit
Length	19.0	±0.15	mm
Width	19.0	±0.15	mm
Height	1.50	±0.30	mm
Light Emitting Surface (LES) Diameter	14.5	±0.30	mm

Note: Denoted product information above is only an example

(LC019D18030: LC019D, CRI80+, 3000K)

5. Reliability Test Items & Conditions

a) Test Items

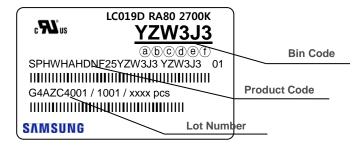
Test Item	Test Condition	Test Hour / Cycle
High Temperature Humidity Life Test	60 °C, 90 % RH,, DC Derating, I _F	1000 h
High Temperature Life Test	85 °C, DC Derating, I _F	1000 h
Low Temperature Life Test	-40 °C, DC , I _F = 970 mA	1000 h
Pulsed Operating Life Test	55 °C, Pulse width 100 μs, duty cycle 3 %	1000 h
High Temperature Storage	120 °C	1000 h
Low Temperature Storage	-40 °C	1000 h
Temperature Humidity Storage	60 °C, 90% RH	1000h
Temperature Cycle On/Off Test	-40 °C / 85 °C each 20 min, 30 min transfer power on/off each 5 min, DC Derating, I_F = max	100 cycles
ESD (HBM)	$\begin{array}{ccc} R_1; & 10 \text{ M}\Omega \\ R_2; & 1.5 \text{ k}\Omega \\ \text{C}; & 100 \text{ pF} \\ \text{V}; & \pm 2 \text{ kV} \end{array}$	5 times
ESD (MM)	$$R_{1}$: 10 M\Omega$ $	5 times
Vibration Test	20 ~ 80 Hz (displacement: 0.06 inch, max. 20 g) 80 ~ 2 kHz (max. 20 g) min. frequency ↔ max. frequency 4 min transfer	4 times
Mechanical Shock Test	1500 g, 0.5 ms each of the 6 surfaces (3 axis x 2 sides)	5 times
Sulfur Resistance	25 °C, 75%, H2S 15 ppm	504h

b) Criteria for Judging the Damage

ltem	Symbol	Test Condition	Lin	Limit	
item	Зушьог	(T _c = 25 °C)	Min.	Max.	
Forward Voltage	V_{F}	I _F = 540 mA	L.S.L. * 0.9	U.S.L. * 1.1	
Luminous Flux	Φ _ν	I _F = 540 mA	L.S.L * 0.7	U.S.L * 1.3	

6. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 5)

Bin Code:

(a) (refer to page 11)

©d: Chromaticity bin (refer to page 9-10)

(e) f): Luminous Flux bin (refer to page 6)

b) Lot Number

The lot number is composed of the following characters:



① 3456789 / 1abc / xxxx pcs

: Production site (S: Giheung, Korea, G: Tianjin, China)

② : 4 (LED)

③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

(4) : Year (Z: 2015, A: 2016, B: 2017...)

5 : Month (1~9, A, B, C)

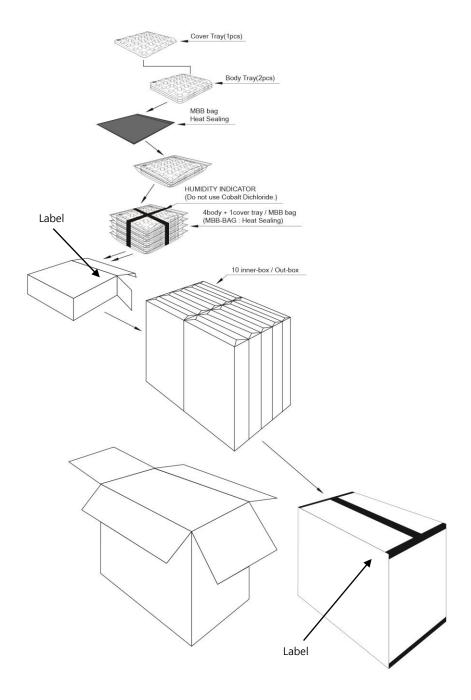
6789 : Day (1~9, A, B~V)

(a)b)C : Product serial number (001 ~ 999)

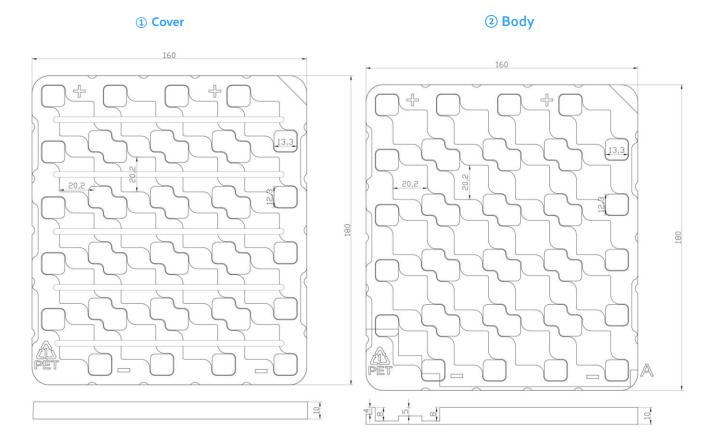
6. Packing Structure

	Max. quantity	Dimension(mm)			
Packing material	in pcs of COB	Length	Width	Height	Tolerance
Tray	20	160	180	10	1.0
Aluminum Bag	40(2 trays)	210	241		10
Inner Box	160	230	84	260	2
Outer Box	1600	476	445	272	5

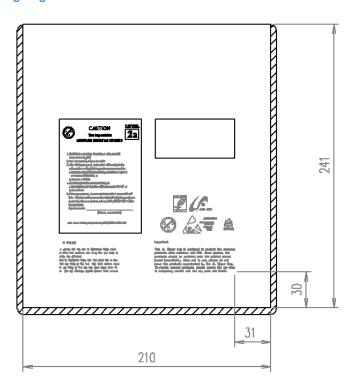
a) Packing Structure



b) Tray

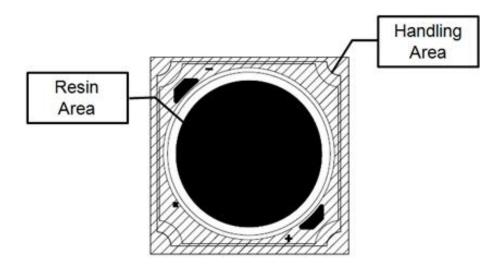


c) Aluminum Vinyl Packing Bag



8. Precautions in Handling & Use

- This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA
 is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the
 device.
- 2) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- 3) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH, or
 - b. Stored at <10 % RH
- 4) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 5) Devices require baking before mounting, if humidity card reading is >60 % at 23 \pm 5 °C.
- 6) Devices must be baked for 1 hour at 60 ± 5 °C, if baking is required.
- 7) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 8) The thermal management is one of the most critical factors for the LED lighting system. Especially the LED junction temperature should not exceed the absolute maximum rating while operation of LED lighting system.
 - For more information, please refer to Application Note 'Mechanical & Thermal Guide for COB'.
- 9) In case of driving LEDs around the minimum current level (If_min), chips might exhibit different brightness due to the variation in I-V characteristics of each one. This is normal and does not adversely affect the performance of product.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) The resin area is very sensitive, please do not handle, press, touch, rub, clean, or pick by with tweezers on it. Instead, please pick at the handling area as indicated below.



Legal and additional information.

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Samsung Electronics Co., Ltd. 95, Samsung 2-ro Giheung-gu Yongin-si, Gyeonggi-do, 446-711 KOREA

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